



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**Notification# 20160823005
Datasheet update for SN54HC32, SN74HC32
Information Only Datasheet**

Date: 8/31/2016
To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

20160823005
Information Only Datasheet
Attachments


Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
SN74HC32DBR	null
SN74HC32N	null
SN74HC32NSR	null
SN74HC32PWR	null

Technical details of this Product Change follow on the next page(s).

Notification Number:	20160823005	Notification Date:	Aug.31, 2016
Title:	Datasheet update for SN54HC32, SN74HC32		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details							
Description of Change:							
<p>Texas Instruments Incorporated is announcing an information only notification.</p> <p>The product datasheet(s) is being updated as summarized below.</p> <p>The following change history provides further details.</p>							
 <div style="text-align: right;"> SN54HC32, SN74HC32 <small>SCLS200E – DECEMBER 1982 – REVISED JULY 2016</small> </div>							
Changes from Revision D (August 2003) to Revision E	Page						
<ul style="list-style-type: none"> Added ESD Ratings table, Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section Removed Ordering Information table Updated values in the Thermal Information tables to align with JEDEC standards 	1 1 5						
<p>The datasheet number will be changing.</p> <table border="1" style="width: 100%;"> <tr> <td>Device Family</td> <td>Change From:</td> <td>Change To:</td> </tr> <tr> <td>SN54HC32, SN74HC32</td> <td>SCLS136D</td> <td>SCLS136E</td> </tr> </table>		Device Family	Change From:	Change To:	SN54HC32, SN74HC32	SCLS136D	SCLS136E
Device Family	Change From:	Change To:					
SN54HC32, SN74HC32	SCLS136D	SCLS136E					
<p>These changes may be reviewed at the datasheet links provided.</p> <p>http://www.ti.com/product/SN74HC32</p>							

Reason for Change:			
To more accurately reflect device characteristics.			
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):			
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.			
Changes to product identification resulting from this PCN:			
None.			
Product Affected:			
SN74HC32D	SN74HC32DRE4	SN74HC32NSR	SN74HC32PWRE4
SN74HC32DBR	SN74HC32DRG4	SN74HC32PW	SN74HC32PWRG4
SN74HC32DE4	SN74HC32DT	SN74HC32PWE4	SN74HC32PWT
SN74HC32DG4	SN74HC32N	SN74HC32PWG4	SN74HC32PWTG4

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com